



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-01-15
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	marianna grasso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99DZ200G	HF9J*UBFKAA5	A	959	2021-01-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	260	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	DM00688157	



Package Designator	Size	Nbr of instances	Shape	
QFP	10.00,10.00,1.40	64	gull wing	
Comment	LQFP 64 10x10x1.4 1.0 ExPad Down. MDF valid for CPs: L99DZ200G,L99DZ200GTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.26	die - leadframe	981

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	HF9J*UBFKAAS					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	19.815	mg	supplier	die	Silicon(Si)	7440-21-3		17.847	mg	900681	68642
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.042	mg	2120	162
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.010	mg	505	38
				supplier	metallisation	Copper(Cu)	7440-50-8		1.105	mg	55766	4250
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.002	mg	101	8
				supplier	metallisation	Gold(Au)	7440-57-5		0.027	mg	1363	104
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.187	mg	9437	719
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.043	mg	2170	165
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.007	mg	353	27
				supplier	metallisation	Tungsten(W)	7440-33-7		0.063	mg	3179	242
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	151	12
				supplier	passivation	Silicon oxide	7631-86-9		0.274	mg	13828	1054
				supplier	polymer coating	Polyimide AH 1200	proprietary		0.205	mg	10346	788
				Leadframe	M-004 Copper and its alloys	99.628	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8	
supplier	alloy & coating	Nickel(Ni)	7440-02-0						0.068	mg	683	262
supplier	alloy & coating	Iron(Fe)	7439-89-6						2.282	mg	22905	8777
supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8						0.137	mg	1375	527
supplier	alloy & coating	Zinc(Zn)	7440-66-6						0.120	mg	1204	462
supplier	alloy & coating	Silver (Ag)	7440-22-4						0.001	mg	10	4
supplier	alloy & coating	Palladium(Pd)	7440-05-3						0.002	mg	20	8
supplier	alloy & coating	Gold(Au)	7440-57-5						0.001	mg	10	4
supplier	alloy & coating	Silver(Ag)	7440-22-4						2.461	mg	891990	9465
Die attach	M-011 Other inorganic materials	2.759	mg	supplier	glue or tape (choose)	Isobornyl Methacrylate	7534-94-3		0.207	mg	75027	796
				supplier	glue or tape	Bismaleimide resin	proprietary		0.083	mg	30083	319
				supplier	glue or tape	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.008	mg	2900	31
				supplier	wire	Copper(Cu)	7440-50-8		2.762	mg	1000000	10623
Bonding wires	M-004 Copper and its alloys	2.762	mg	supplier	wire	Copper(Cu)	7440-50-8		2.762	mg	1000000	10623
Bonding wires 2	M-004 Copper and its alloys	2.130	mg	supplier	wire	Copper(Cu)	7440-50-8		2.130	mg	1000000	8192
Encapsulation	M-011 Other inorganic materials	132.906	mg	supplier	mold compound	Silica vitreous	60676-86-0		108.252	mg	814500	416354
				supplier	mold compound	Silicon oxide	7631-86-9		9.968	mg	75000	38338
				supplier	mold compound	Epoxy type resin	proprietary		9.968	mg	75000	38338
				supplier	mold compound	Phenol type resin	proprietary		3.987	mg	30000	15335
				supplier	mold compound	Carbon black	1333-86-4		0.731	mg	5500	2812